

REMARKS

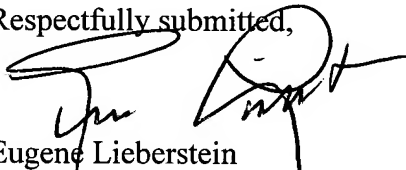
This Preliminary Amendment is being filed concurrently with the filing of the above-identified new patent application to amend the title.

The current title, METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES, is being amended to read as follows:

--METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES AND A CLAMPING DEVICE FOR MANUFACTURING A SEMICONDUCTOR PACKAGE--.

Applicant respectfully submits that no new matter is being added by way of the Preliminary Amendment and respectfully requests entry thereof.

Respectfully submitted,



Eugene Lieberstein
Reg. No. 24,645

ANDERSON, KILL & OLICK
1251 Avenue of the Americas
New York, New York 10020-1182
(212) 278-1000

MAILING CERTIFICATE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as Express Mail in an envelope addressed: Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450, Mail Stop Patent Applications on April 20, 2004.



Date: April 20, 2004